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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/708,932	11/08/2000	Salman Akram	3434.1US (97-856.1) 4170		
<sup>24247</sup> TRASK BF	7590 07/08/2002		EXAMI	NER	
P.O. BOX 2550 SALT LAKE CITY, UT 84110			MACKEY, JAMES P		
Star End	J		ART UNIT	PAPER NUMBER	
			1722	P	
			DATE MAILED: 07/08/2002	· 6	

Please find below and/or attached an Office communication concerning this application or proceeding.

PTO-90C (Rev. 07-01)

Office Action Summary

Application No. 09/708,932

Applicant(s)

Examiner

James Mackey

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**AKRAM** 

		James	3 Mackey		
	The MAILING DATE of this communication appear	rs on the cover si	heet with t	he corres	pondence address
Dariad (			_		
A SH THE I  Extens mailing If the If NO Failure	For Reply ORTENED STATUTORY PERIOD FOR REPLY IS SI MAILING DATE OF THIS COMMUNICATION.  Gions of time may be available under the provisions of 37 CFR 1.136 (a).  Go date of this communication.  Period for reply is specified above is less than thirty (30) days, a reply with period for reply is specified above, the maximum statutory period will appear to reply within the set or extended period for reply will, by statute, causely received by the Office later than three months after the mailing date of patent term adjustment. See 37 CFR 1.704(b).	In no event, however,	may a reply be n of thirty (30 B) MONTHS frome ABANDO	e timely filed ) days will b om the maili (NED (35 U.S	e considered timely.  ng date of this communication.  S.C. § 133).
Status					. 1
1) 🗆					
2a) 🗆		action is non-fin			ting as to the marite is
3) 🗆	Since this application is in condition for allowand closed in accordance with the practice under Ex	ce except for for parte Quayle, 1	mal matte 935 C.D.	ers, prose 11; 453	8 O.G. 213.
Dispos	sition of Claims			is/ar	re pending in the application.
4) 💢	Claim(s) <u>1-41</u>			13,01	withdrawn from consideration.
	4a) Of the above, claim(s)			IS/8	is/are allowed.
5) 🗆	Claim(s)				is/are rejected
6) 💢	Claim(s) <u>1-41</u>				_ is/are rejected.
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8) [	Claim(s)	;	are subjec	t to rest	riction and/or election requirements
Appli	cation Papers				
9)[	The specification is objected to by the Examine	er.		·	and to by the Evaminer
10)[	The specification is objected to by the Exemitation.  The drawing(s) filed onis	s/are a) 🗌 acce	pted or b	) Lobjed	cted to by the Examiner.
		AL - demainale) he	hold in ah	evance.	See 37 CFN 1.00ta/.
11)5	- A service perception filed on A	ug 13, 2001	is: a) XI	approve	d bin disapproved by the Exemine
40)[	I was in abjected to by the F	examiner.			
12)	. at u.o.o. \$5,410 and 120				
Prior	ity under 35 U.S.C. 33 119 and 120  Acknowledgement is made of a claim for fore	ign priority unde	r 35 U.S.(	C. § 119	(a)-(d) or (f).
	a) □ All b) □ Some* c) □ None of:				
`	1 Certified copies of the priority document	s have been rec	eived.		
	a Contified copies of the priority document	ts have been rec	eived in A	pplicatio	n No
	3. Copies of the certified copies of the prior	rity documents I I Bureau (PCT Ri	nave been Jle 17.2(a	received )).	IN fulls Mational Stage
	*See the attached detailed Office action for a list	nestic priority un	der 35 U.	S.C. § 1	19(e).
14)	<ul> <li>Acknowledgement is made of a claim for don</li> <li>a)</li> <li>The translation of the foreign language prov</li> </ul>	visional application	on has bee	en receiv	ed.
	a) ☐ The translation of the foreign language proc ☐ Acknowledgement is made of a claim for dor	nestic priority ur	nder 35 U.	S.C. §§	120 and/or 121.
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	chment(s)  Notice of References Cited (PTO-892)				Paper No(s)
	Notice of Draftsperson's Patent Drawing Review (PTO-948)	5) Notice	of Informal P	atent Applica	ation (PTO-152)
3)	Information Disclosure Statement(s) (PTO-1449) Paper No(s). 2,3	6) Other	:	_	
1 "	73				

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1. Claims 4, 5, 21, 22, 32, 33 and 38 are objected to under 37 CFR 1.75(c), as being of improper dependent form for failing to further limit the subject matter of a previous claim.

Applicant is required to cancel the claim(s), or amend the claim(s) to place the claim(s) in proper dependent form, or rewrite the claim(s) in independent form.

Claims 4, 5, 21, 22, 32 and 33 only recite the functioning of the claimed apparatus during its intended operation, and the contents of the claimed apparatus during its intended operation; such does not set forth additional structure of the claimed apparatus and relates only to the intended use of the claimed apparatus, which does not patentably distinguish the claimed apparatus structure, and therefore does not further limit the subject matter of the apparatus claims. Note that intended use has been continuously held not to be germane to determining the patentability of the apparatus, *In re Finsterwalder*, 168 USPQ 530. The manner or method in which a machine is to be utilized is not germane to the issue of patentability of the machine itself, *In re Casey*, 152 USPQ 235. Purpose to which apparatus is to be put and expression relating apparatus to contents thereof during intended operation are not significant in determining patentability of an apparatus claim, *Ex parte Thibault*, 164 USPQ 666.

Claim 38 only recites a limitation regarding the product intended to be produced by the claimed apparatus; such does not set forth additional structure of the claimed apparatus and relates only to the intended use of the claimed apparatus, which does not patentably distinguish the claimed apparatus structure, and therefore does not further limit the subject matter of the apparatus claims.

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2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 3. Claims 1-5, 16, 18-24, 27, 29-33, 37, 38 and 41 are rejected under 35 U.S.C. 102(b) as being clearly anticipated by Ochiai et al. (U.S. Patent 5,643,831; col. 4, lines 57-60, and col. 6, lines 16-17). Note that Ochiai et al. clearly teach that the mold substrate plate is heated (col. 4, line 66), inherently teaching a heating element (claim 24) to accomplish such a heating function.
- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 6-11, 17, 25, 26, 28 and 34-36 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ochiai et al. (U.S. Patent 5,643,831).

Ochiai et al. '831 teaches the mold apparatus substantially as claimed, except for the cavity depth being "about 28 micrometers" (claims 6, 25, 34), except for the protective layer thickness being "from about 200 Angstroms to 5 micrometers" (claims 7, 26, 35), except for the particular shape of the cavity (claims 8-11, 36), and except for the mold substrate comprising ceramic material (claims 17 and 28).

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However, Ochiai et al. '831 explicitly discloses cavity depths of 70 to 100 micrometers (col. 6, line 62), and further discloses the relationship between cavity depth and the length of the side of the cavity mouth (col. 6, lines 63-67), including graphically correlating the side length to cavity depths of between 0-100 micrometers (as clearly shown in Figure 13), and Ochiai et al. also discloses the utility of forming solder bumps having a thickness of "several tens of  $\mu$ m" (col. 2, lines 38-39); therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention to modify Ochiai et al. by providing a cavity depth of about 28  $\mu$ m, since Ochiai et al. recognize the utility of solder bump products of similar thickness, and since Ochiai et al. disclose side lengths of the cavity mouth for a range of cavity depth which clearly overlaps the claimed cavity depth (see Figure 13).

Additionally, Ochiai et al. '831 (Figures 2-3) shows a protective layer thickness approximately corresponding to the upper end of the claimed thickness range. Therefore, it would have been obvious to a skilled artisan to have provided the silicon mold substrate with a silicon oxide or silicon nitride protective layer by oxidizing or nitriding the silicon mold substrate to a protective layer thickness within the claimed range in order to inexpensively produce the protective layer and to minimize altering the cavity shape/depth by the protective layer.

With regard to the shape of the cavity, trapezoidal, hemispherical, square and rectangular shaped cavities are conventional in the molding art for mold cavities for producing solder balls, and therefore it would have been obvious and well within the level of ordinary skill in the art to have provided the wedge-shaped, rhomboid-mouthed cavity of Ochiai et al. '831 in such

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conventional shapes, since each of the cavity shapes has recognized utility for forming solder balls. Furthermore, mold substrates formed of ceramic material are also conventional in the molding art for mold substrates for producing solder balls, and therefore it would have been obvious and well within the level of ordinary skill in the art to have provided the mold substrate of Ochiai et al. '831 of a ceramic material, since such is a recognized equivalent to silicon for use as a mold substrate for producing solder balls.

6. Claims 12-15, 39 and 40 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ochiai et al. (U.S. Patent 5,643,831) in view of Bolstad (U.S. Patent 2,979,773; column 2, lines 5-14).

Ochiai et al. '831 teaches the mold apparatus substantially as claimed, including disclosing that the mold substrate plate is heated (col. 4, line 66), except for disclosing a heater strip or plural heater strips located on another surface of the mold substrate. Bolstad discloses heater strips for efficiently providing heat to a semiconductor mold material 22. It would have been obvious to one of ordinary skill in the art at the time of the invention to modify Ochiai et al. by providing heater strips on the exterior of the mold substrate, as suggested by Bolstad, in order to efficiently provide heat to the mold substrate plate as desired by Ochiai et al.

- 7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.
- 8. Any inquiry concerning this communication or earlier communications from the examiner should be directed to James Mackey whose telephone number is (703) 308-1195. The examiner can normally be reached on Monday-Friday from 8:30AM to 6:00PM. If attempts to reach the

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examiner by telephone are unsuccessful, the examiner's supervisor, Mr. Jan Silbaugh, can be reached at (703) 308-3829. The fax phone number for this Group is (703) 305-7718.

Any inquiry of a general nature or relating to the status of this application should be directed to the Group receptionist whose telephone number is (703) 308-0651. Any inquiry relating to the contents or papers filed in this application, other than issues of substance requiring the attention of the Examiner, should be directed to the Customer Service Office, Technology Center 1700, whose telephone number is (703) 306-5665.

MACKEY/jpm June 28, 2002 JAMES MACKEY
PRIMARY EXAMINER

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6/28/02